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AUIRL2203N

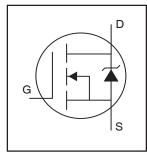
### **Features**

- Advanced Planar Technology
- Low On-Resistance
- Logic Level Gate Drive
- Dynamic dV/dT Rating
- 175°C Operating Temperature
- Fast Switching
- · Fully Avalanche Rated
- · Repetitive Avalanche Allowed up to Tjmax
- · Lead-Free, RoHS Compliant
- Automotive Qualified \*

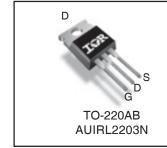
### **Description**

Specifically designed for Automotive applications, this stripe planar design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low on-resistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.

### HEXFET® Power MOSFET



V <sub>(BR)DSS</sub>	30V
R <sub>DS(on)</sub> max.	<b>7m</b> Ω
D (Silicon Limited)	116A®
I <sub>D (Package Limited)</sub>	75A



G	D	S
Gate	Drain	Source

Base part number	Bookege Type	Standa	rd Pack	Orderable Part Number
Base part number	Package Type	Form	Quantity	Orderable Part Number
AUIRL2203N	TO-220	Tube	50	AUIRL2203N

### **Absolute Maximum Ratings**

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T<sub>A</sub>) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
I <sub>D</sub> @ T <sub>C</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V (Silicon Limited)	116 <sup>©</sup>	
I <sub>D</sub> @ T <sub>C</sub> = 100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V (Silicon Limited)	82©	Α
I <sub>D</sub> @ T <sub>C</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V (Package Limited)	75	
I <sub>DM</sub>	Pulsed Drain Current ①	400	
P <sub>D</sub> @T <sub>C</sub> = 25°C	Power Dissipation	180	W
	Linear Derating Factor	1.2	W/°C
V <sub>GS</sub>	Gate-to-Source Voltage	±16	V
E <sub>AS</sub>	Single Pulse Avalanche Energy ②⑤	290	mJ
I <sub>AR</sub>	Avalanche Current ①	60	Α
E <sub>AR</sub>	Repetitive Avalanche Energy ①	18	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5.0	V/ns
ТЈ	Operating Junction and	FF 12 . 17F	
T <sub>STG</sub>	Storage Temperature Range	-55 to + 175	°C
	Soldering Temperature, for 10 seconds	300 (1.6mm from case )	
	Mounting Torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)	

### **Thermal Resistance**

	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Junction-to-Case		0.85	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.50		C/VV

HEXFET® is a registered trademark of International Rectifier.

<sup>\*</sup>Qualification standards can be found at http://www.irf.com/



### Static Electrical Characteristics @ $T_J = 25$ °C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	30			V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient		0.029		V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance			7.0		V <sub>GS</sub> = 10V, I <sub>D</sub> = 60A <sup>(4)</sup>
				10	mΩ	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 48A ⊕
V <sub>GS(th)</sub>	Gate Threshold Voltage	1.0			V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$
gfs	Forward Transconductance	73			S	V <sub>DS</sub> = 25V, I <sub>D</sub> = 60A <sup>⊕</sup>
I <sub>DSS</sub>	Drain-to-Source Leakage Current			25	μΑ	$V_{DS} = 30V$ , $V_{GS} = 0V$
				250		$V_{DS} = 24V, V_{GS} = 0V, T_{J} = 125^{\circ}C$
I <sub>GSS</sub>	Gate-to-Source Forward Leakage			100	nA	V <sub>GS</sub> = 16V
	Gate-to-Source Reverse Leakage			-100	1	V <sub>GS</sub> = -16V

### Dynamic Electrical Characteristics @ T<sub>.i</sub> = 25°C (unless otherwise specified)

<del>- Dynamic</del>	y name Electrical characteristics & 1j = 20 c (amess calefwise specifica)					
$Q_g$	Total Gate Charge			60		$I_D = 60A$
$Q_{gs}$	Gate-to-Source Charge			14	nC	V <sub>DS</sub> = 24V
$Q_{gd}$	Gate-to-Drain ("Miller") Charge			33		V <sub>GS</sub> = 4.5V, See Fig.6 and 13 <sup>⊕</sup>
t <sub>d(on)</sub>	Turn-On Delay Time		11			V <sub>DD</sub> = 15V
t <sub>r</sub>	Rise Time		160			$I_D = 60A$
t <sub>d(off)</sub>	Turn-Off Delay Time		23		ns	$R_G = 1.8\Omega$
t <sub>f</sub>	Fall Time		66			V <sub>GS</sub> = 4.5V,, See Fig.10
L <sub>D</sub>	Internal Drain Inductance		4.5			Between lead,
					nH	6mm (0.25in.)
L <sub>S</sub>	Internal Source Inductance	l	7.5			Between lead,
			7.5			and center of die contact
C <sub>iss</sub>	Input Capacitance		3290			$V_{GS} = 0V$
C <sub>oss</sub>	Output Capacitance		1270		pF	$V_{DS} = 25V$
C <sub>rss</sub>	Reverse Transfer Capacitance		170			f = 1.0MHz, See Fig.5

#### **Diode Characteristics**

	Parameter	Min.	Тур.	Max.	Units	Conditions
IS	Continuous Source Current			116©		MOSFET symbol
	(Body Diode)			110@		showing the
I <sub>SM</sub>	Pulsed Source Current			400		integral reverse
	(Body Diode) ①			400		p-n junction diode.
$V_{SD}$	Diode Forward Voltage			1.2	V	$T_J = 25^{\circ}C$ , $I_S = 60A$ , $V_{GS} = 0V$ ④
t <sub>rr</sub>	Reverse Recovery Time		56	84	ns	$T_J = 25^{\circ}C, I_F = 60A$
Q <sub>rr</sub>	Reverse Recovery Charge		110	170	nC	di/dt = 100A/µs <sup>④</sup>
t <sub>on</sub>	Forward Turn-On Time	Intrinsic	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)			

### Notes:

- $\ensuremath{\mathbb{O}}$  Repetitive rating; pulse width limited by max. junction temperature. ( See fig. 11 )
- $\odot$  Starting  $T_J$  = 25°C, L = 0.16mH,  $~R_G$  = 25 $\Omega,~I_{AS}$  = 60A,  $V_{GS}$  =10V (See Figure 12)
- $\label{eq:local_local_special} \text{$\Im$} \quad I_{SD} \leq 60 \text{A, di/dt} \leq 110 \text{A/}\mu\text{s, } V_{DD} \leq V_{(BR)DSS}, \, T_J \leq 175^{\circ}\text{C}$
- $\odot$  This is a calculated value limited to  $T_J = 175^{\circ}C$ .
- © Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 75A.



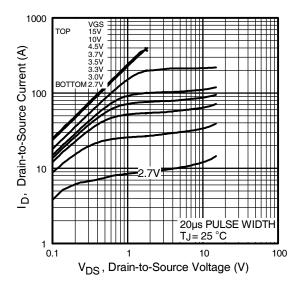


Fig 1. Typical Output Characteristics

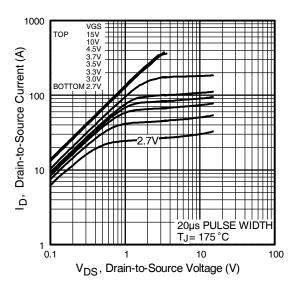


Fig 2. Typical Output Characteristics

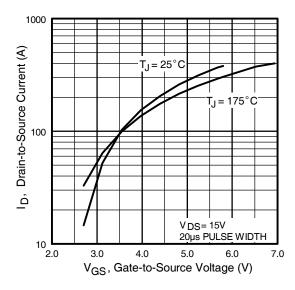
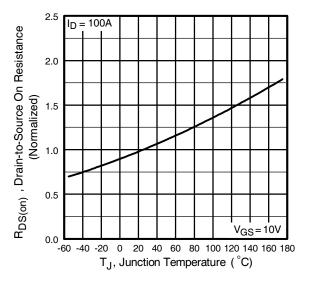
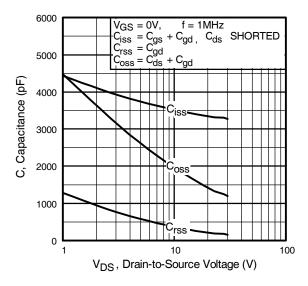


Fig 3. Typical Transfer Characteristics

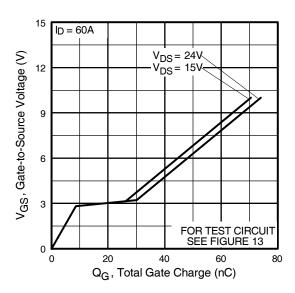


**Fig 4.** Normalized On-Resistance Vs. Temperature

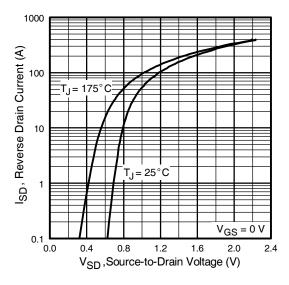




**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



**Fig 7.** Typical Source-Drain Diode Forward Voltage

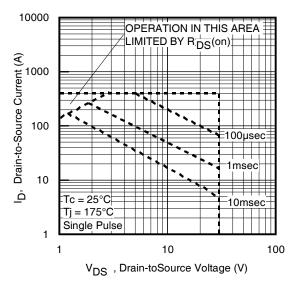
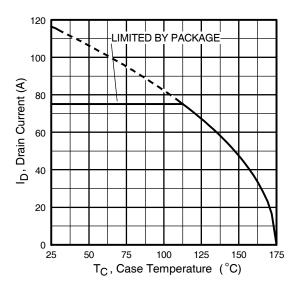


Fig 8. Maximum Safe Operating Area





**Fig 9.** Maximum Drain Current Vs. Case Temperature

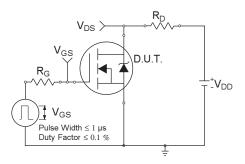


Fig 10a. Switching Time Test Circuit

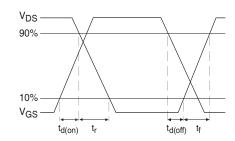


Fig 10b. Switching Time Waveforms

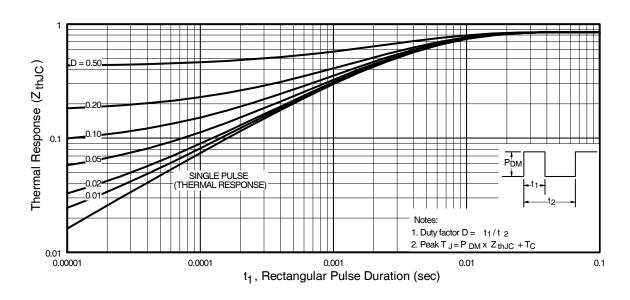


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case



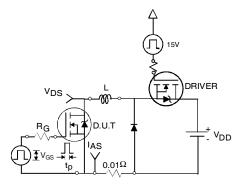


Fig 12a. Unclamped Inductive Test Circuit

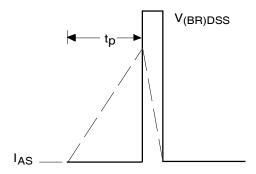


Fig 12b. Unclamped Inductive Waveforms

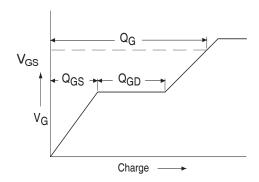


Fig 13a. Basic Gate Charge Waveform

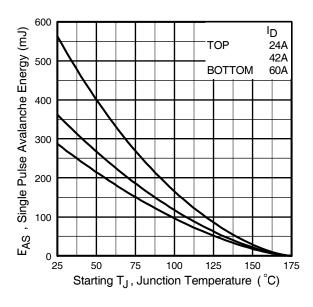


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

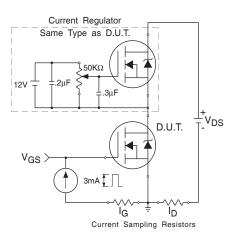
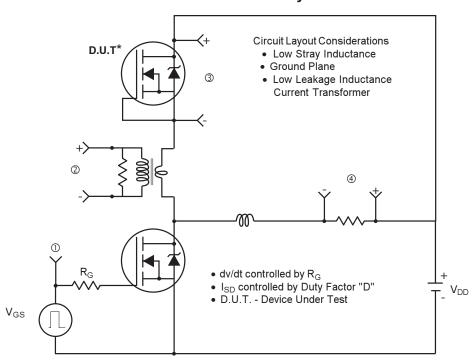


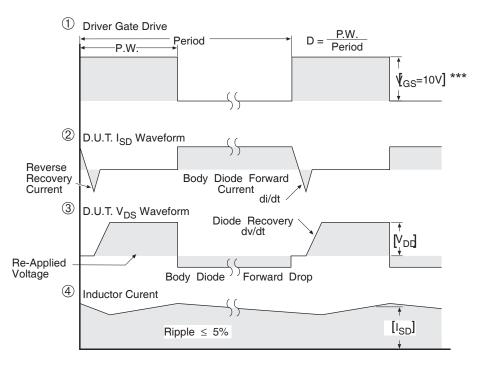
Fig 13b. Gate Charge Test Circuit



## Peak Diode Recovery dv/dt Test Circuit



<sup>\*</sup> Reverse Polarity of D.U.T for P-Channel



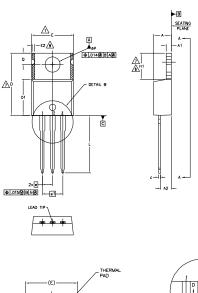
\*\*\* V<sub>GS</sub> = 5.0V for Logic Level and 3V Drive Devices

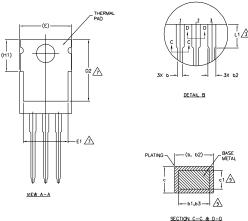
Fig 14. For N-channel HEXFET® power MOSFETs



# TO-220AB Package Outline

Dimensions are shown in millimeters (inches)





#### NOTES:

- 1.- DIMENSIONING AND TOLERANCING AS PER ASME Y14.5 M- 1994.
- 2.- DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
  3.- LEAD DIMENSION AND FINISH UNCONTROLLED IN L1.
- DIMENSION D, D1 & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- DIMENSION 61, 63 & c1 APPLY TO BASE METAL ONLY.
- CONTROLLING DIMENSION: INCHES.
- THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E,H1,D2 & E1
- DIMENSION E2 X H1 DEFINE A ZONE WHERE STAMPING AND SINGULATION IRREGULARITIES ARE ALLOWED.
- OUTLINE CONFORMS TO JEDEC TO-220, EXCEPT A2 (max.) AND D2 (min.) WHERE DIMENSIONS ARE DERIVED FROM THE ACTUAL PACKAGE OUTLINE.

SYMBOL	MILLIMETERS		INC	HES	
	MIN.	MAX.	MIN.	MAX.	NOTES
A	3.56	4.83	.140	.190	
A1	1,14	1.40	.045	.055	
A2	2.03	2.92	.080	.115	
b	0.38	1.01	.015	.040	
ь1	0.38	0.97	.015	.038	5
b2	1,14	1.78	.045	.070	
b3	1,14	1.73	.045	.068	5
С	0.36	0.61	.014	.024	
c1	0.36	0.56	.014	.022	5
D	14.22	16.51	.560	.650	4
D1	8.38	9.02	.330	.355	
D2	11,68	12.88	.460	.507	7
E	9.65	10.67	.380	.420	4,7
E1	6.86	8.89	.270	.350	7
E2	-	0.76	-	.030	8
е	2.54 BSC		.100	BSC	
e1	5.08	BSC	.200	BSC	
H1	5,84	6.86	.230	.270	7,8
L	12.70	14.73	.500	.580	
L1	3.56	4.06	.140	.160	3
øΡ	3,54	4.08	.139	.161	
Q	2.54	3.42	.100	.135	

#### LEAD ASSIGNMENTS

HEXFET 1.- GATE 2.- DRAIN 3.- SOURCE

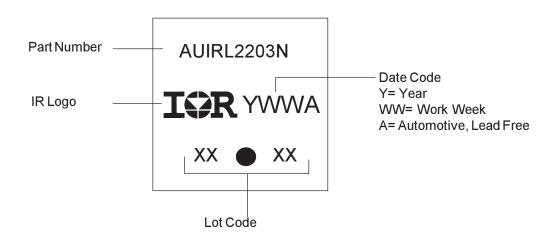
### IGBTs, CoPACK

1,- GATE 2.- COLLECTOR 3.- EMITTER

### DIODES

1,- ANODE 2.- CATHODE 3.- ANODE

# TO-220AB Part Marking Information



Note: For the most current drawing please refer to IR website at http://www.irf.com/package/



# **Qualification Information**<sup>†</sup>

		Automotive (per AEC-Q101) ††			
		Comments: This part number(s) passed Automotive qualification IR's Industrial and Consumer qualification level is granted b extension of the higher Automotive level.			
Moisture Sensitivity Level		3L-TO-220 N/A			
	Machine Model		Class M3(+/- 400V ) <sup>†††</sup> (per AEC-Q101-002)		
ESD	Human Body Model		Class H1C(+/- 2000V ) <sup>†††</sup> (per AEC-Q101-001)		
	Charged Device Model	Class C5(+/- 2000V ) <sup>†††</sup> (per AEC-Q101-005)			
RoHS Compliant		Yes			

<sup>†</sup> Qualification standards can be found at International Rectifier's web site: <a href="http://www.irf.com/">http://www.irf.com/</a>

<sup>††</sup> Exceptions (if any) to AEC-Q101 requirements are noted in the qualification report.

<sup>†††</sup> Highest passing voltage



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For technical support, please contact IR's Technical Assistance Center <a href="http://www.irf.com/technical-info/">http://www.irf.com/technical-info/</a>

#### **WORLD HEADQUARTERS:**

101 N. Sepulveda Blvd., El Segundo, California 90245 Tel: (310) 252-7105



### **Revision History**

110 VIOLOTT THOUGHT						
Date	Comments					
	Added "Logic Level Gate Drive" bullet in the features section on page 1					
3/25/2014	Updated Package Outline and Part Marking on page 8					
	Updated data sheet with new IR corporate template					